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(12) **United States Design Patent**
Collins et al.

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(54) **COMBINED COMPUTER MODULE AND DOCK**

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(**) Term: **15 Years**

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Related U.S. Application Data

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(51) **LOC (12) Cl.** **14-02**

(52) **U.S. Cl.**
USPC **D14/434; D14/314**

(58) **Field of Classification Search**
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D14/240, 299, 496, 314, 356, 357, 358,
D14/209.1, 171, 300, 341, 344; D21/333;
D13/103, 107, 108, 133, 135, 184;
D3/201, 215, 216, 218, 227; D29/101.1
CPC G06F 1/16; G06F 1/162; G06F 1/1626;
G06F 1/163; G06F 1/1632; G06F 1/1688;
G06F 13/00; H01M 10/44; F16M 11/10;
F16M 11/20

See application file for complete search history.

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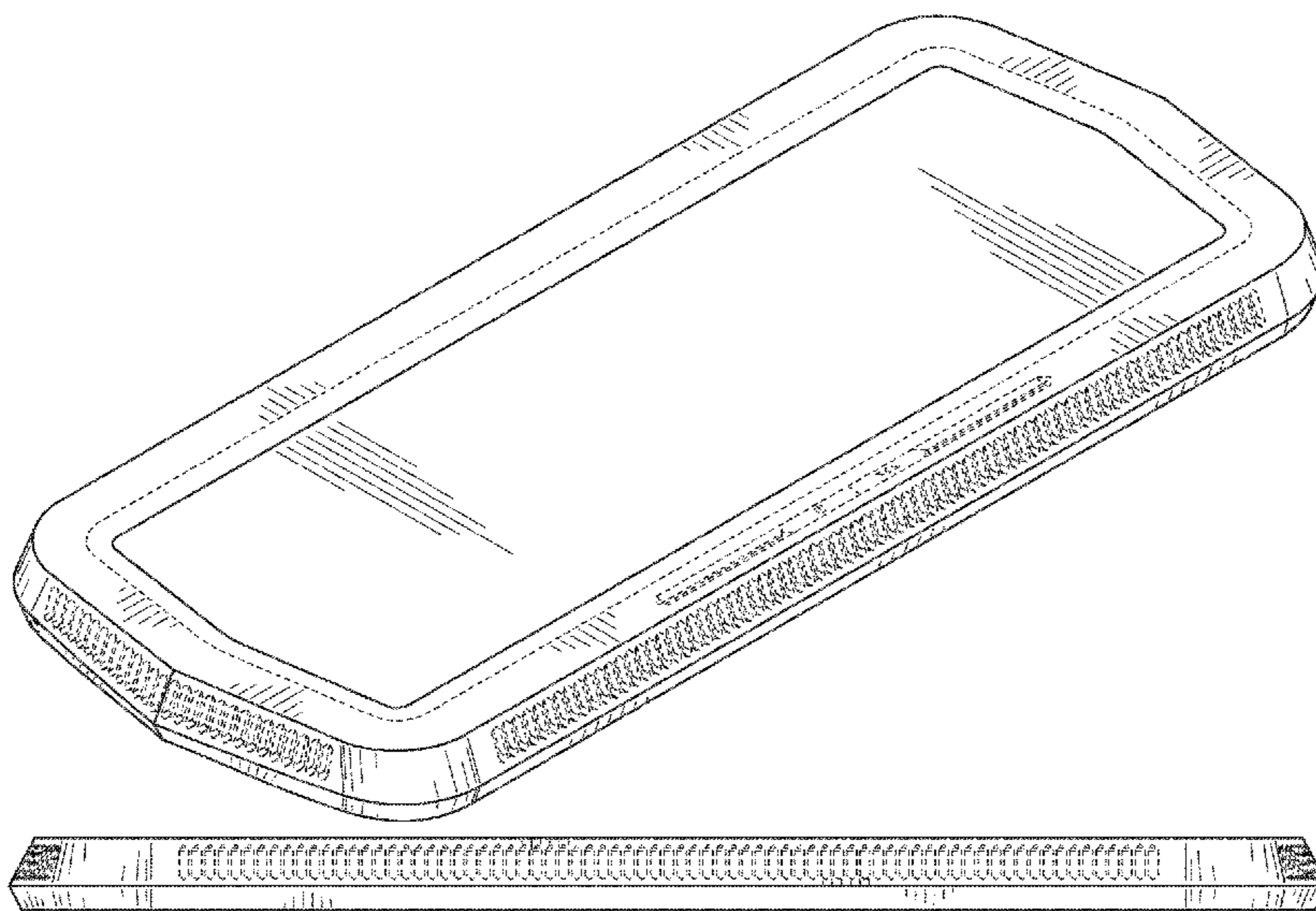
(57) **CLAIM**

The ornamental design for a “combined computer module and dock”, as shown and described in FIGS. 1-9.

DESCRIPTION

FIG. 1 is a top, right perspective view of a combined computer module and dock, showing our new design; FIG. 2 is a bottom, left perspective view thereof; FIG. 3 is a front view thereof; FIG. 4 is a rear view thereof; FIG. 5 is a right side thereof; FIG. 6 is a left side view thereof; FIG. 7 is a top view thereof; FIG. 8 is a bottom view thereof; and, FIG. 9 is another top, right perspective view thereof, shown in an exploded position for clarity. The features of the combined computer module and dock shown in broken lines form no part of the claimed design.

1 Claim, 6 Drawing Sheets



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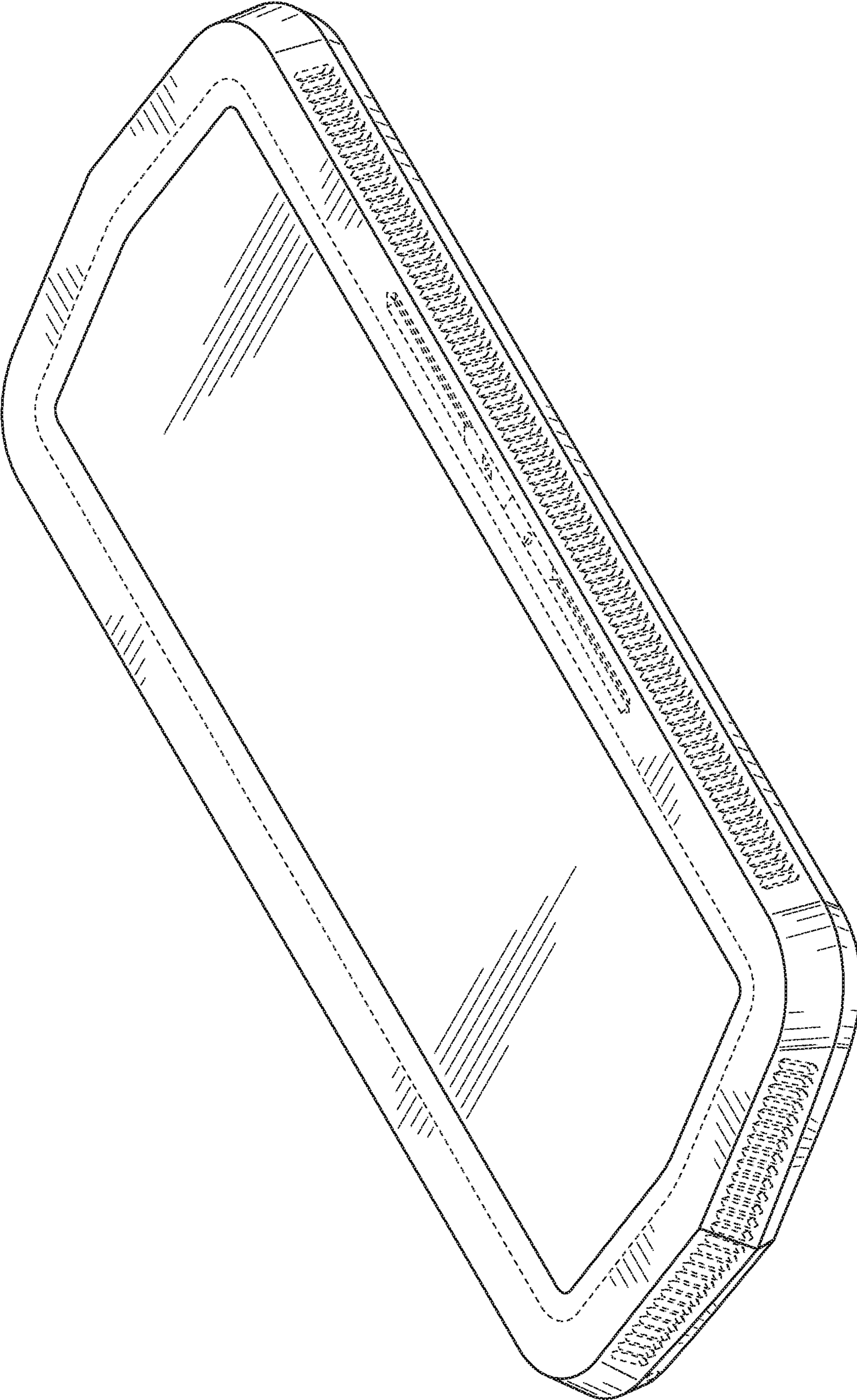


FIG. 1

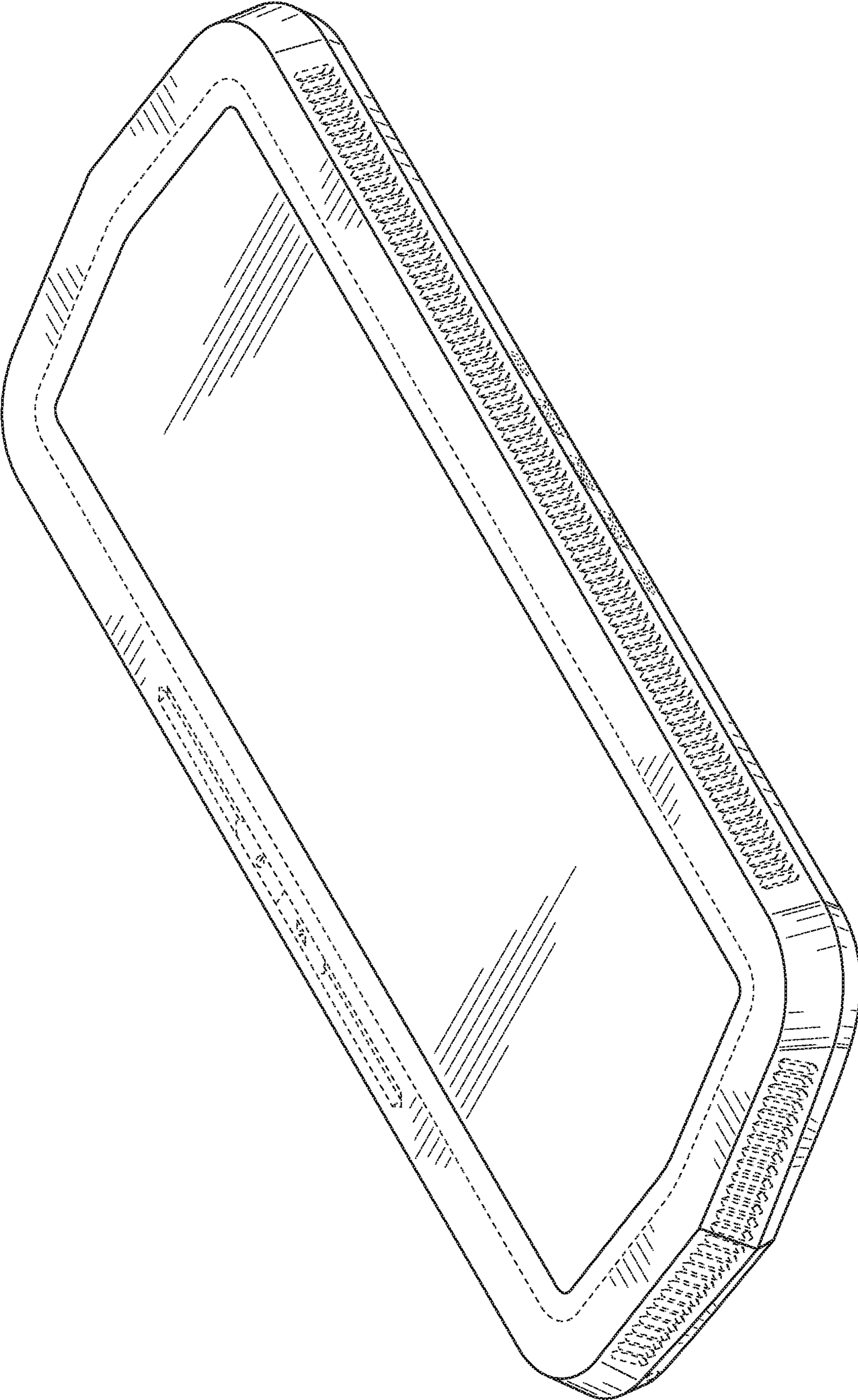


FIG. 2

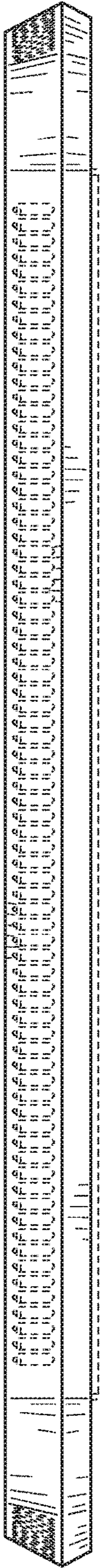


FIG. 3

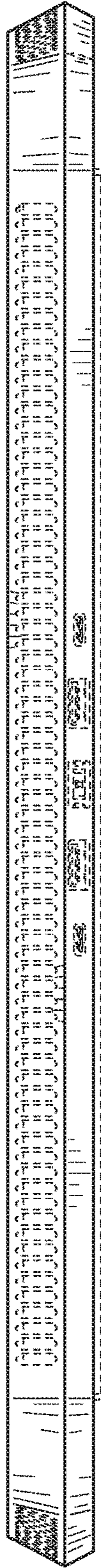


FIG. 4

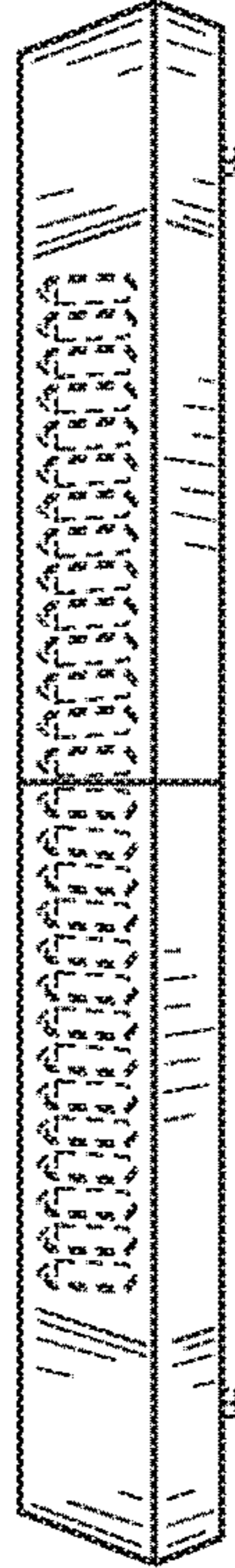


FIG. 5

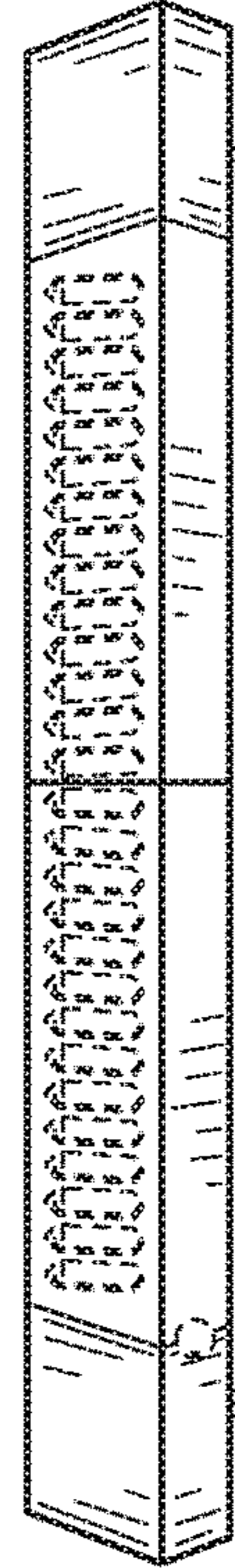


FIG. 6

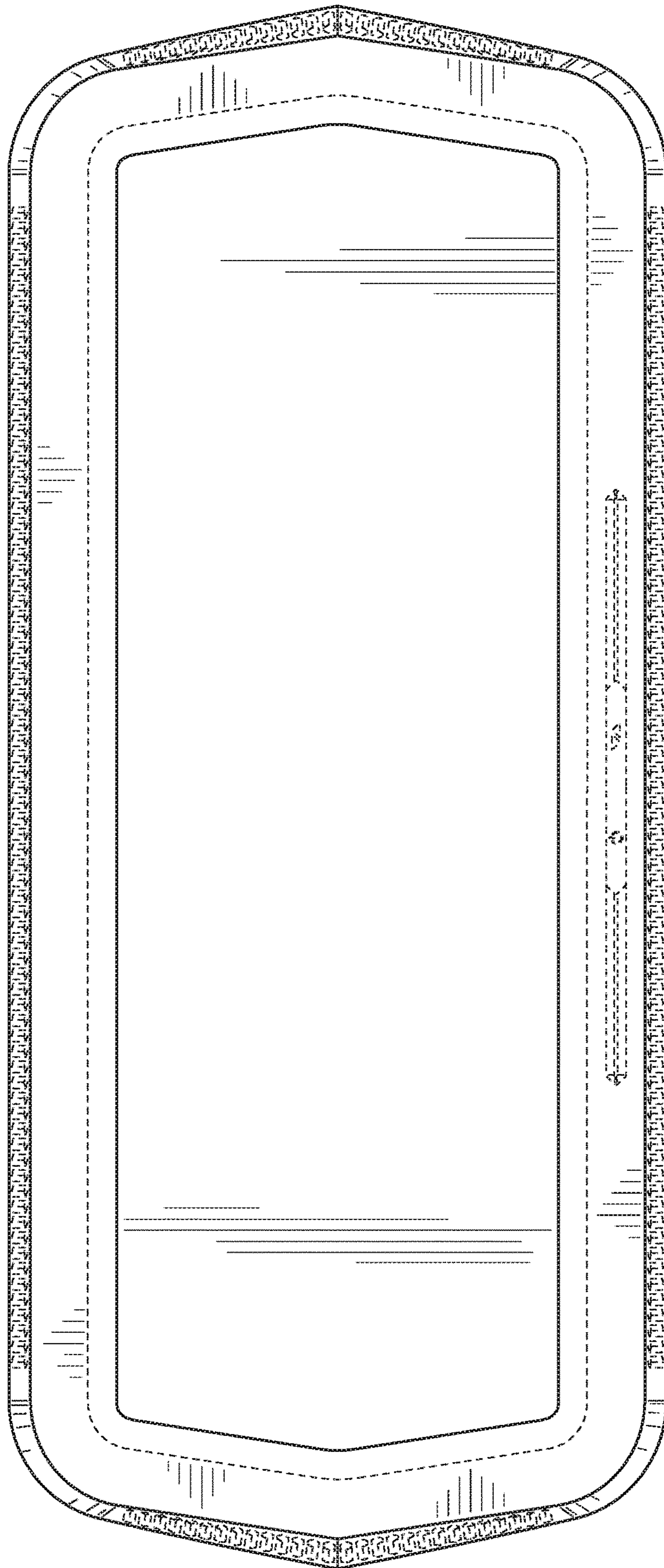


FIG. 7

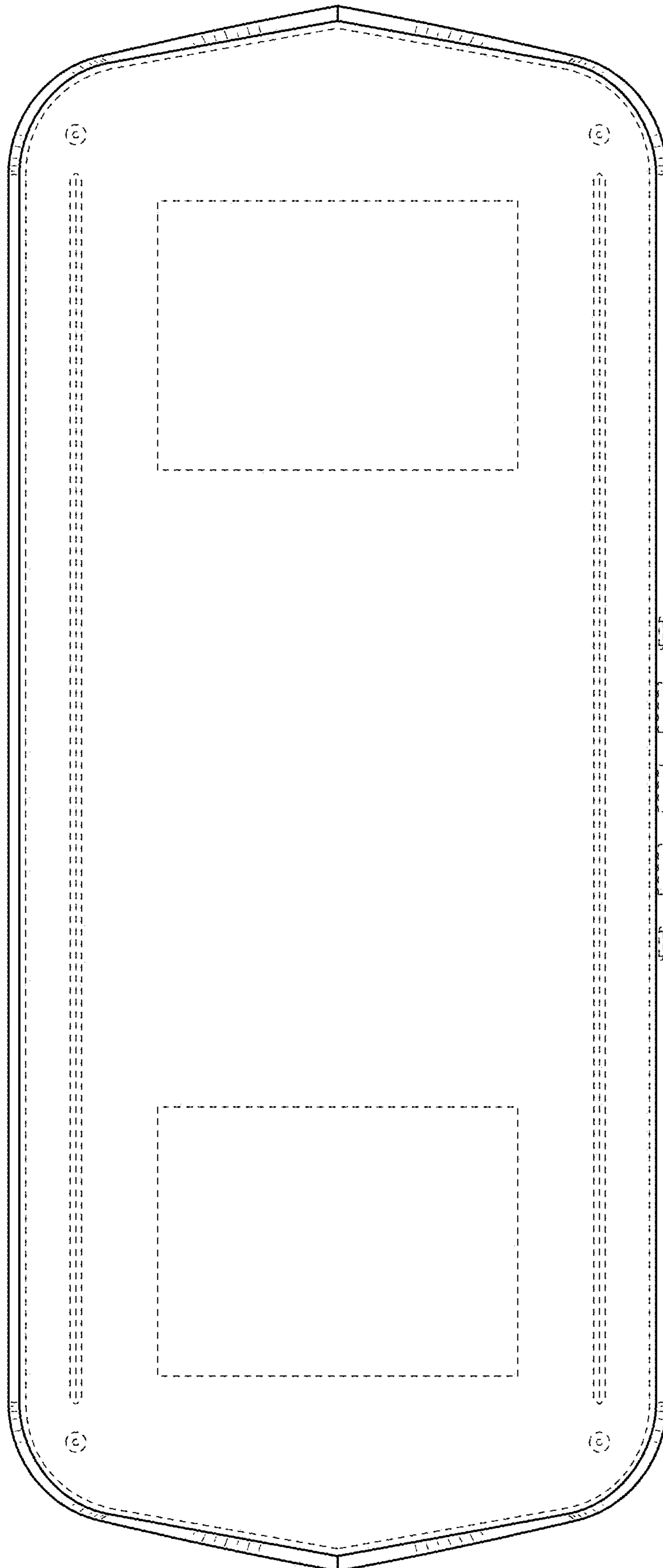


FIG. 8

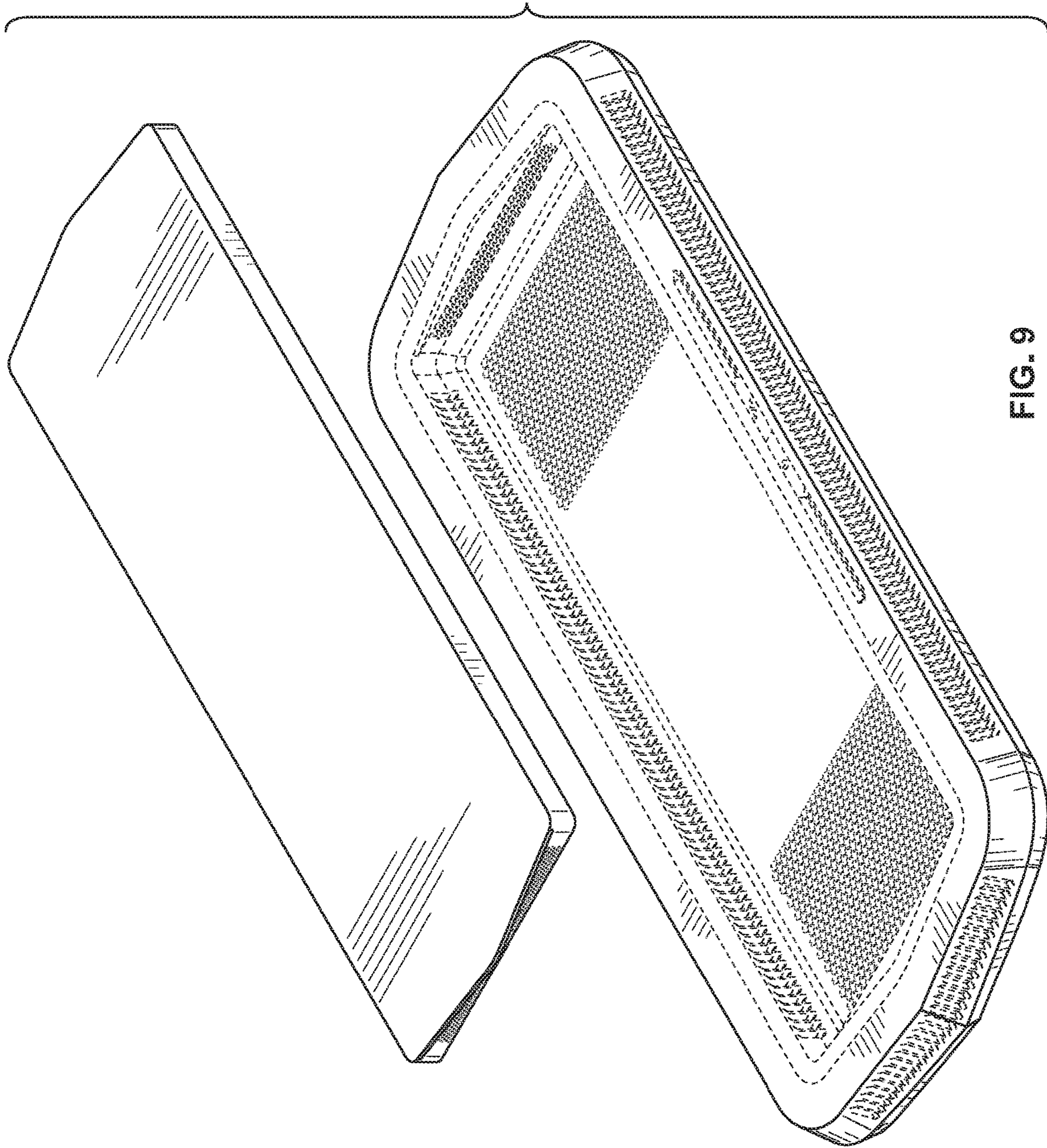


FIG. 9